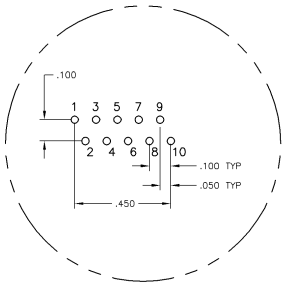
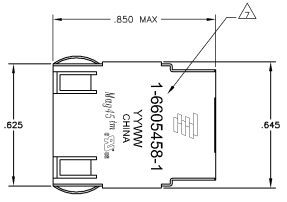
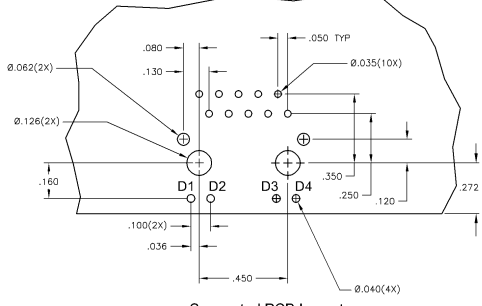
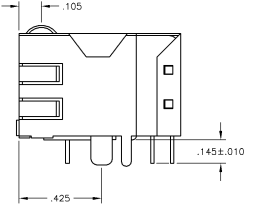
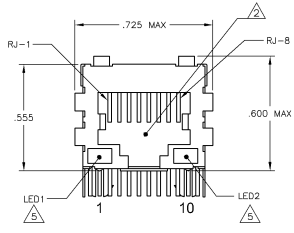


MECHANICAL:



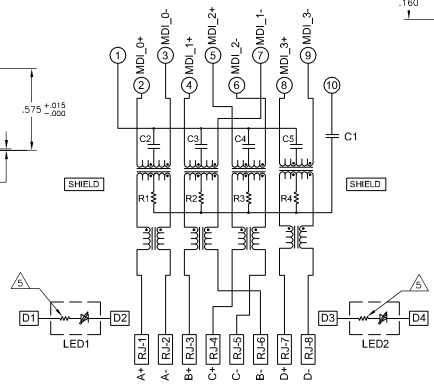
Pin Designations



Suggested PCB Layout (Component Side)

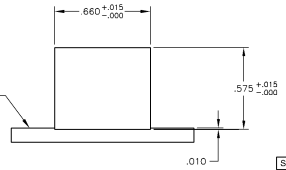
- △ MATERIALS: HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0. SHIELD - .010" THICK (26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER. MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDER TABS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP. LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 4.0μINCH NICKEL UNDERPLATE OVER 4.0μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
- △ RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
- △ MAGNETICS: -IMPEDANCE: 100 OHMS -TURNS RATIO (CHIP-CABLE): 1:1 ALL FOUR PAIRS -OPEN CIRCUIT INDUCTANCE (OCL): 350nH MIN @100MHz, 0.1VRMS. -BIAS BIAS FROM 0°C TO 70°C, ALL FOUR PAIRS -ALL FOUR PAIRS BI-DIRECTIONAL -PERFORMANCE @ 25°C: INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz 12-20LOG|f|/80dB MIN FROM 4.0MHz TO 100MHz CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz 33-20*LOG|f|/50dB MIN FROM 4.0MHz TO 100MHz COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz -ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 40.6.11, ITEM b.
- 4 OPERATING TEMPERATURE: FROM 0°C - -70°C.
- △ LEDS WITH BUILT-IN RESISTOR LEDS ARE DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA. LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ VF=5V FORWARD CURRENT (IF): GREEN 12mA TYP @ VF=5V
- △ THE MAGNETICS ARE SYMMETRICAL, AND SUPPORT AUTO-MDIX/MDIX.
- △ TYCO ELECTRONICS LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
- 8 THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

4G02 GIGABIT MAGNETIC CIRCUIT



C1=1000 pF, 2KV CAPACITOR
R1-R4 = 75 OHMS, 1/16 W RESISTORS
C2-C5 = 0.1 uF, 50V CAPACITORS

Suggested Panel Cutout



GREEN		GREEN		1-6605458-1	
LED1		LED2		PART NUMBER	
THIS DRAWING IS A CONTROLLED DOCUMENT					
DATE	REV	DESCRIPTION	BY	CHKD	APPROV
10/22/2008	1	1X1 MAG452TM MODULAR JACK (10 PIN HORIZ), 402 SCHEMATIC, 4G02 GIGABIT CIRCUIT, SHIELDED, DECOUPLING CAPACITOR, WITH RESISTOR LEADS			
10/22/2008	2	REV PER ECO-09-000008			
CUSTOMER DRAWING					